

## PENDING CLAIMS

1-2. (cancelled)

3. (previously presented) A method comprising:  
forming a plurality of image sensor die having micro-lenses onto a semiconductor wafer, wherein said image sensor die uses a ball grid array (BGA) on the underside of said die;  
forming a protective layer over said image sensor die;  
dicing said wafer to separate said plurality of image sensor die;  
mounting said image sensor die onto an integrated circuit package; and  
removing said protective layer from said image sensor die.

4-5. (cancelled)